

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Myung-Beom PARK	09/26/2011
Jung-Sik CHOI	09/26/2011
Ki-Hyeon KIM	09/26/2011
Yuji MORISHIMA	10/25/2011
Shin-ichi TANAKA	10/24/2011
Takashi YAMADA	10/24/2011
Takehiro ZUSHI	10/25/2011

RECEIVING PARTY DATA

Name:	Samsung Electronics Co., Ltd.
Street Address:	416, Maetan-dong, Yeongtong-gu
City:	Suwon-si, Gyeonggi-do
State/Country:	REPUBLIC OF KOREA

Name:	ADEKA CORPORATION
Street Address:	7-2-35 HIGASHI-OGU
Internal Address:	ARAKAWA-KU
City:	TOKYO
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13290520

CORRESPONDENCE DATA

Fax Number: (703)207-0003

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

OP \$40.00 13290520

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PATENT
REEL: 027185 FRAME: 0476

via US Mail.

Correspondent Name: Eugene M. Lee
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Address Line 2: 3141 Fairview Park Drive, Suite 500
Address Line 4: Falls Church, VIRGINIA 22042

ATTORNEY DOCKET NUMBER:	262/108
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NAME OF SUBMITTER:	Eugene M. Lee
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Total Attachments: 4

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ASSIGNMENT

Name and Address of Assignee	<p>For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, each undersigned inventor has sold and assigned, and by these presents hereby sells and assigns, unto</p> <p>SAMSUNG ELECTRONICS CO., LTD., 416, Maetan-dong, Yeongtong-gu Suwon-si, Gyeonggi-do, Republic of Korea</p> <p>And ADEKA CORPORATION 7-2-35, Higashi-ogu, Arakawa-ku, Tokyo, Japan</p>
	(hereinafter ASSIGNEE) all right, title and interest for the United States, its territories and possessions in and to his invention relating to

Title of Invention	COPPER ELECTROPLATING METHOD as set forth in this United States Patent Application
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Check One	<input type="checkbox"/> executed concurrently herewith
	<input type="checkbox"/> executed on _____
	<input type="checkbox"/> Serial No. _____ Filed _____

in and to said United States Patent Application including any and all divisions or continuations thereof and in and to any and all Letters Patent of the United States which may issue on any such application or for said invention, including any and all reissues or extensions thereof, to be held and enjoyed by said ASSIGNEE, its successors, legal representatives and assigns to the full end of the term or terms for which any and all such Letters Patent may be granted as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made;

Each of the undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent to said ASSIGNEE, its successors or assigns in accordance herewith;

Each of the undersigned warrants and covenants that he has the full and unencumbered right to sell and assign the interests herein sold and assigned and that he has not executed and will not execute any document or instrument in conflict herewith;

Each of the undersigned further covenants and agrees he will communicate to said ASSIGNEE, its successors, legal representatives or assigns all information known to him relating to said invention or patent application and that he will execute and deliver any papers, make all rightful oaths, testify in any legal proceedings and perform all other lawful acts deemed necessary or desirable by said ASSIGNEE, its successors, legal representatives or assigns to perfect title to said invention, to said application including divisions and continuations thereof and to any and all Letters Patent which may be granted therefore or thereon, including reissues or extensions, in said ASSIGNEE, its successors, or assigns or to assist said ASSIGNEE, its successors, legal representatives or assigns in obtaining, reissuing or enforcing Letters Patent of the United States for said invention;

Each of the undersigned hereby grants the firm of LEE & MORSE, P.C. the power to insert in this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office for recordation of this Assignment.

NAMES AND SIGNATURES OF INVENTORS		
Name: Myung-Beom PARK	Signature: Myung-Beom Park	Date: 09/26/2011
Name: Jung-Sik CHOI	Signature: Jung-Sik Choi	Date: 09/26/2011
Name: Ki-Hyeon KIM	Signature: Ki-Hyeon Kim	Date: 09/26/2011
Name: Yuji MORISHIMA	Signature:	Date:
Name: Shin-ichi TANAKA	Signature:	Date:
Name: Takashi YAMADA	Signature:	Date:
Name: Takehiro ZUSHI	Signature:	Date:
NAMES AND SIGNATURES OF WITNESSES		

Name:	Signature:	Date:
Name:	Signature:	Date:

Note: *Prima facie* evidence of execution may optionally be obtained by execution of this document before a U.S. Consul or before a local officer authorized to administer oaths whose authority is proved by a certificate from a U.S. Consul.

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	(hereinafter ASSIGNEE) all right, title and interest for the United States, its territories and possessions in and to his invention relating to

Title of Invention	<p>COPPER ELECTROPLATING METHOD as set forth in this United States Patent Application</p>
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Each of the undersigned hereby grants the firm of LEE & MORSE, P.C. the power to insert in this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office for recordation of this Assignment.

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Name: <i>Jung-Sik CHOI</i>	Signature: _____	Date: _____
Name: <i>Ki-Hyeon KIM</i>	Signature: _____	Date: _____
Name: <i>Yuji MORISHIMA</i>	Signature: <i>森島 裕司</i>	Date: <i>10/25/2011</i>
Name: <i>Shin-ichi TANAKA</i>	Signature: <i>田中 伸一</i>	Date: <i>10/24/2011</i>
Name: <i>Takashi YAMADA</i>	Signature: <i>山田 孝志</i>	Date: <i>10/24/2011</i>
Name: <i>Takehiro ZUSHI</i>	Signature: <i>角 知子</i>	Date: <i>10/25/2011</i>
NAMES AND SIGNATURES OF WITNESSES		

Name:	Signature:	Date:
Name:	Signature:	Date:

Note: *Prima facie* evidence of execution may optionally be obtained by execution of this document before a U.S. Consul or before a local officer authorized to administer oaths whose authority is proved by a certificate from a U.S. Consul.